ALPHA® CVP-520 SOLDER PASTE

Low Melting Point, No-Clean, Lead-Free, Zero Halogen

DESCRIPTION

ALPHA CVP-520 is designed to enable low temperature surface mount assembly technology. The lead-free alloy in **ALPHA CVP-520** has a melting point below 140 °C, and has been successfully used with peak reflow profiles between 155 °C and 190 °C. The flux residue from **ALPHA CVP-520** is clear, colorless, and provides excellent electrical resistivity, exceeding industry standards.

This product enables the elimination of an extra wave or selective wave soldering process when temperature sensitive through hole components are used in an assembly. Eliminating a wave soldering or selective soldering step can significantly lower the cost of producing an electronic assembly, increase daily throughput, eliminate the need for managing bar solder and wave soldering flux supplies and eliminate the need for pallets. The carefully selected Sn/Bi/Ag alloy in **ALPHA CVP-520** was selected to give the lowest melting point, lowest pasty range during melting and re-solidification, along with a very fine grain structure, offering maximum resistance to thermal cycle based fatigue. The alloy also yields very low voiding BGA solder joints, even when a traditional SAC alloy sphere is used.

The use of ALPHA Exactalloy® Performs may enable the elimination of selective wave soldering by providing additional solder volume when needed.

All components used with **ALPHA CVP-520** must be lead-free to eliminate the formation of tin/lead/bismuth intermetallic which has a melting point under 100 ºC.

READ ENTIRE TECHNICAL DATA SHEET BEFORE USING THIS PRODUCT

FEATURES & BENEFITS

- Enables elimination of a second or third reflow cycle when temperature sensitive components or connectors are used
- Reduces energy consumption in reflow ovens versus standard lead-free alloys
- Reduces reflow process cycle time
- Delivers 8-hour stencil life
- Potential eliminations of bar solder, wave soldering flux and energy costs associated with wave soldering
- Compatible with all commonly used lead-free surface finishes (ENTEK HT; Alpha Star Immersion Silver, Immersion Tin, Ni/Au, SACX HASL, etc.)

- Excellent resistance to random solder balling minimizing rework and increasing first time yield
- Low temperature reflow profiles may enable the use of less expensive printed circuit board substrates, when appropriate
- Meets highest IPC-7095 voiding performance (Class 3).
- Provides excellent electrical reliability properties
- Zero-halogen (no halogen intentionally added) and halide-free material
- Compatible with either nitrogen or air reflow

PRODUCT INFORMATION

Alloys:	42%Sn/57.6%Bi/0.4%Ag
	42%Sn/57%Bi/1.0%Ag, available upon request
Powder Size:	Type 3, Type 4, Type 5
Residues:	Approximately 5% by (w/w)
Packaging Sizes:	500-gram jars, 6 inch & 12 inch cartridges
Flux Gel:	ALPHA CVP-520 Flux Gel is available in 10 cc and 30 cc syringes for rework applications.
Lead Free:	RoHS Directive EU/2015/863; amending Annex II of 2011/65/EU

APPLICATION GUIDELINES

Formulated for both standard and fine pitch stencil printing, at print speeds of between 40 mm/sec (1.5 in/sec) and 100 mm/sec (4 in/sec), with stencil thickness of 0.100 mm (0.004 in) to 0.150 mm (0.006 in), particularly when used in conjunction with ALPHA Stencils. Blade pressures should be 0.18 to 0.27 kg/cm of blade (1.0 to 1.5 lb/inch), depending upon the print speed. The higher the print speed employed, the higher the blade pressure that is required to prevent smearing on the stencil. Examples of successful reflow profiles are outlined below. Generally, peak temperatures of 155 to 190 °C have proven effective.

TECHNICAL DATA

Category	Results	Procedures/Remarks
Chemical Properties		
Activity Level	ROL0 = J-STD Classification	IPC J-STD-004
Halide Content	Halide-free (by titration). Passes Ag Chromate Test	IPC J-STD-004
Halogen Content	Pass, Zero-Halogen - No halogen intentionally added	EN14582, by oxygen bomb combustion, Non-detectable (ND) at < 50 ppm
Copper Mirror Test	Pass	IPC J-STD-004
Copper Corrosion Test	Pass (No Evidence of Corrosion)	IPC J-STD-004
	Pass (No evidence of corrosion)	JIS Z 3197:1999 8.4.1
Electrical Properties		
SIR (7 days @ 85 °C /85% RH, 12V)	Pass, $\geq 10^8$ ohms for 7 days	IPC J-STD-004C TM-650 2.6.3.7
SIR (7 days @ 85 °C /85% RH)	Pass	IPC J-STD-004 {Pass = 1 x 10^8 ohm min}
SIR (96 hrs @ 35 °C /85% RH)	Pass	Bellcore GR78-CORE {Pass = 1x10^{11} ohm min}
Electromigration (1000 hrs @ 85 oC /85% RH 48V DC)	Final Reading > 10^{10} ohms; No Migration After 1000 hr = Pass	JIS Z 3197:1999
Physical Properties		
Color	Clear, Colorless Flux Residue	
Tack Force vs. Humidity (t = 8 hours)	Pass - Change of < 1g/mm^2 over 24 hours at 25% and 75% RH	IPC J-STD-005
	Pass - Change of <10% when stored at 25±2 °C and 50±10% RH	JIS Z 3284 Annex 9
Solderball	Acceptable	IPC J-STD-005
Stencil Life	>8 hours	@ 50% RH, 23 °C (74 °F)
Spread	>87%	JIS Z 3197:1999 8.3.1.1
Slump	Pass	Modified IPC J-STD-005 (10 min 100 °C)

Category	Results	Procedures/Remarks
	Pass	JIS Z-3284:1994 Annex 8

PROCESSING GUIDELINES

Storage & Handling	Printing	Reflow (See Figure #1)	Cleaning
Refrigerate to guarantee stability at 0 to 10 °C (32 to 50 °F), Shelf life of refrigerated paste is (6) months. Paste can be stored for 2 weeks at room temperature up to (25 °C/77 °F) prior to use. When refrigerated, allow paste container to warm to room temperature for up to four hours. Paste must be ≥19 °C (66 °F) before processing. Verify paste temperature with a thermometer to ensure paste is 19 °C (66 °F) or greater before set-up. Printing can be performed at temperatures up to 29 °C (84 °F). Paste can be manually stirred before use. A rotating/ centrifugal force mixing operation is not required. If a rotating/centrifugal force mixing is used, 30 to 60 seconds at 300 RPM is adequate. Do not remove worked paste from stencil and mix with unused paste in jar. This will alter rheology of unused paste. Working conditions: 19 to 29 °C (66 to 84 °F) on the stencil	Stencil: Recommended ALPHA CUT or ALPHA FORM stencils @ 0.100 to 0.150 mm (4 to 6 mil) thick for 0.4 to 0.5 mm (0.016 to 0.020 in) pitch. Stencil design is subject to many process variables. Contact your local Alpha stencil site for advice. Squeegee: Metal (recommended) Pressure: 0.18 to 0.27 kg/cm (1.0 to 1.5 lb/in) of squeegee length Speed: 40 to 100 mm/sec (1.5 to 4 in/sec) Paste Roll: (1.5 to 2.0 cm) diameter and make additions when roll reaches 1-cm, (0.4 in) diameter (min.). Max. roll size will depend upon blade. Exceeding the maximum diameter may cause curtaining (sticking to the squeegee when it is lifted from the stencil). Stencil Release Speed: 3 to 10 mm/sec (0.12 to 0.4 in/sec) Lift Height: 8 to 14 mm (0.31 to 0.55 in)	Atmosphere: Clean-dry air or nitrogen atmosphere. Profile: See Figure #1 Acceptable reflow / coalescence & IPC-7095 Class 3 voiding classification were obtained with the given profile. Note: Refer to component and board supplier data for thermal properties at elevated temperatures. Lower peak temperatures require longer TAL for improved joint cosmetics.	ALPHA CVP-520 residue is designed to remain on the board after reflow. If reflowed residue cleaning is required, ALPHA BC-2200 aqueous cleaner is recommended. For solvent cleaning, agitation for 5 min in the following cleaners is recommended: - ALPHA SM-110E Misprints and stencil cleaning may be done with: - ALPHA SM-110E - ALPHA SM-440 - ALPHA BC-2200 Commercially available electronics assembly cleaner recommendations from Zestron or Kyzen can also be applied. Contact your local Alpha Technical Support for more information.

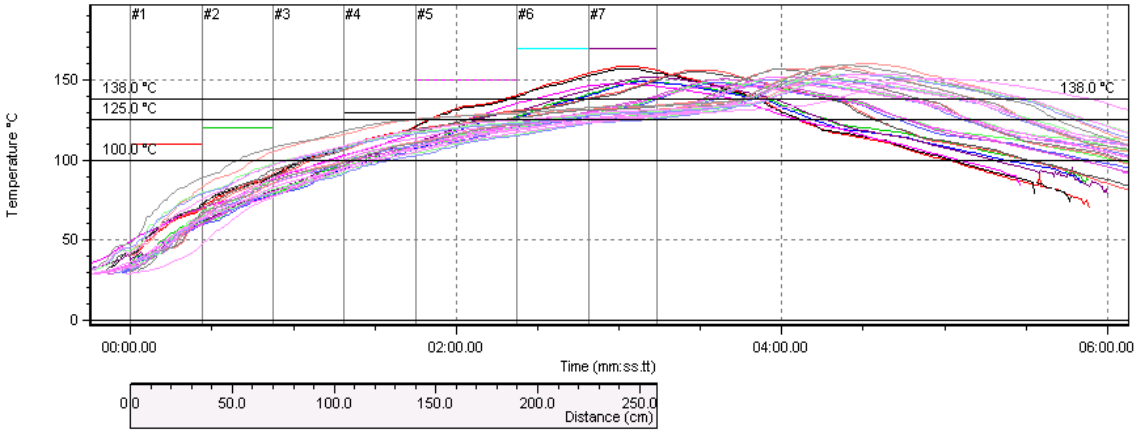
Storage & Handling	Printing	Reflow (See Figure #1)	Cleaning

These are starting recommendations and all process settings should be reviewed independently.

REFLOW PROFILES

General Reflow Profile Guidelines	
Parameter	**Guidelines**
Atmosphere	Air or N2
SnBiAg (42/57.6/0.4) alloy	138 °C (near eutectic)
Setting Zone	**Optimal Dwell Period**
40 to 138 °C	2:10 to 4:00 minutes
125 to 138 °C	0:30 to 1:30 minutes
100 to 138 °C	1:15 to 2:00 minutes
TAL (138 °C)	0:30 to 1:30 minutes
Peak temperature	155 to 180 °C
Joint cool down rate from 170 °C	3 to 8 °C/sec

Figure #1 – CVP-520 Reflow Profile Envelope



RECYCLING SERVICES

We provide safe and efficient recycling services to help companies meet their environmental and legislative requirements and at the same time, maximize the value of their waste streams. Our service collects solder dross, solder scrap, and various forms of solder paste waste. Please contact your local sales representative for recycling capabilities in your area.

SAFETY & WARNING

It is recommended that the company/operator read and review the Safety Data Sheets for the appropriate health and safety warnings before use. **Safety Data Sheets are available.**

STORAGE

ALPHA CVP-520 should be stored in a refrigerator upon receipt at 0 to 10 °C (32 to 50 °F). ALPHA CVP-520 should be permitted to reach room temperature before unsealing its package prior to use (see handling procedures on page 4). This will prevent moisture condensation build up in the solder paste.

CONTACT INFORMATION

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Also read carefully warning and safety information on the Safety Data Sheet. This data sheet contains technical information required for safe and economical operation of this product. READ IT THOROUGHLY PRIOR TO PRODUCT USE . Emergency safety directory assistance: US 1 202 464 2554, Europe + 44 1235 239 670, Asia + 65 3158 1074, Brazil 0800 707 7022 and 0800 172 020, Mexico 01800 002 1400 and (55) 5559 1588